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Atty. Dkt. No. APPM/008269/PPC/ECP/CKIM

IN THE SPECIFICATION:

Please replace paragraph [0036] with the following amended paragraph:

[0036] Drain basin 402 also includes a plurality of substrate centering pins 404 extending upward therefrom. Centering pins 404 are generally positioned radially around the perimeter of drain basin/shield 402 in an equal spacing arrangement, for example. However, the pins 404 may be positioned in any desired spacing arrangement. For example, in the embodiment illustrated in Figure 4, three substrate centering pins 404 are positioned around the perimeter of drain basin 402 at 120° increments[[,]]; however, the pins 404 may be positioned at 20°, 180°, and 340°, for example. The substrate centering pins 404 are generally supported by a substrate centering mechanism positioned below basin 402, which will be further discussed herein, that is configured to both vertically actuate pins 404 and rotationally actuate pins 404 about a longitudinal axis of pins 404, which generally corresponds with the rotational center of pins 404. Bevel clean cell 400 further includes at least one rinsing solution dispensing arm 405, along with at least one etching solution dispensing arm 406. Generally, both arms 405 and 406 are pivotally ~~amounted~~ mounted to a perimeter portion of bevel clean cell 400, and include a longitudinally extending arm having at least one fluid dispensing nozzle positioned on a distal terminating ~~[[in]]~~ end thereof. The nozzles are positioned to dispense the respective processing fluids onto a first or upper side of a substrate positioned on the support member 403. More particularly, when the processing cell 400 is configured as a face-up processing cell, *i.e.*, when substrates are positioned in the cell with the production surface facing away from basin 402, then the fluid dispensing nozzles are configured to dispense their respective fluids onto the production surface of the substrate.

Please replace paragraph [0040] with the following amended paragraph:

[0040] Since each of the receptacles 606 are rotatably mounted within their respective portions of frame member 605, and since each of the lower extending

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portions of receptacles 606 include an actuator 603 and linkage 602 attached thereto, actuation of the primary arm member 604 by actuator 601 causes pivotal movement to actuator arm 604, directly causes the other arms 603 and corresponding receptacles 606 to correspondingly pivot with the primary arm 604. More particularly, each receptacle 606 receives a substrate centering pin 404, and when actuator 601 pivots via primary arm 604, the corresponding receptacles 606 above arms 604 are also pivoted. Further, since linkage 602 ~~can ask~~ connects the secondary pivot arms 603 to the primary pivot arms 604, pivotal movement of the primary pivot arm 604 translates to a corresponding pivotal movement to the secondary pivot arm 603, which directly results in pivotal or rotational movement of the receptacles 606 positioned above the secondary arms 603. This configuration allows for each of the substrate centering pins to be rotatably actuated simultaneously, and for the actuation/rotation to be identical between the three substrate centering pins. Further, each of the receptacles 606 may be vertically actuated, via, for example, vertical movement of the entire centering mechanism 600, or alternatively, via vertical slidable movement of the receptacles 606 within frame 605.

Please replace paragraph [0051] with the following amended paragraph:

[0051] With the substrate chucked and secured, fluid processing may begin. The fluid processing generally includes pivoting the rinsing solution arm 405 to a position approximately above the center of the substrate. The rinsing solution may then be dispensed therefrom while the substrate is rotated on the chuck 403. The rotation causes the rinsing solution, which may be DI water, for example, to be urged radially outward toward the perimeter of the substrate. The rinsing solution flows over the bevel edge of the substrate and falls onto drain basin 402, ~~[[were]]~~ where it may be collected by a drain (not shown). A chemical dispensing arm 406 may also be positioned above the substrate, ~~[[in]]~~ more particularly, the chemical dispensing ~~[[all]]~~ arm 406 may be specifically positioned such that an etchant solution may be dispensed therefrom onto the interface between the production surface and the exclusion zone of the substrate. The process of dispensing the etchant solution onto the interface generally includes

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terminating the dispensing of the rinsing solution from arm 405, and initiating the dispensing of the etchant solution from arm 406. This methodology allows the rinsing solution previously dispensed onto the production surface to maintain a barrier or shield layer on the production surface, which may act to dilute any etchant that may splash back onto the production surface. Further, termination of the rinsing solution dispensing process prior to dispensing the etchant and also operates to prevent unwanted dilution of the etchant solution.